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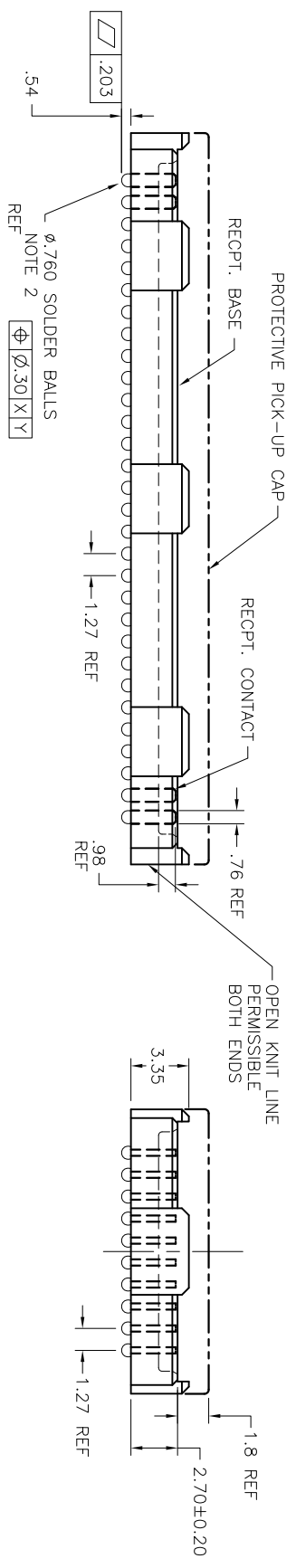
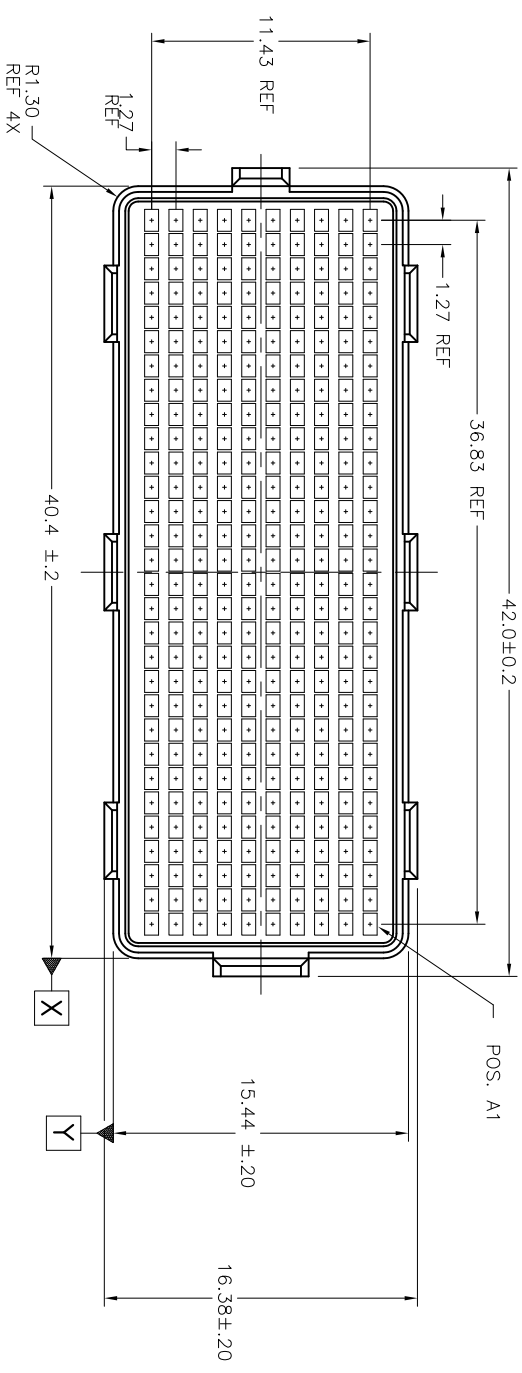


PRODUCT NUMBER
SEE TABLE

1 | 2

3 |

4



mat'l code	SEE NOTE 1	surface	tolerance	projection	product family
lfr	ecm no.	dfr	date	ASME Y14.5	MEG-ARRAY
				ASME Y14.5	
				angles	
				tolerances unless otherwise specified	
L	V11-0028	HTB	2011-06-02	X&E3	
M	V-012333	RE	2012-07-30	XXX.13	
N	V-13453-	DCH	2012-11-14	XXX.051	
P	V-13453-	DCH	2012-02-06		
R	V-18087	DCH	2014-02-25		
S	V-26025	RWD	2017-02-06		
Sheet	revision	S	S	S	
index	Sheet	1	2	3	4



Scale: 3:1

dwg no
10 X 30 = 300 POS.

sheet 1 of 4

84501

CUSTOMER Drawing

A4

form: A4mmX1c

1 |

2 |

3 |

4



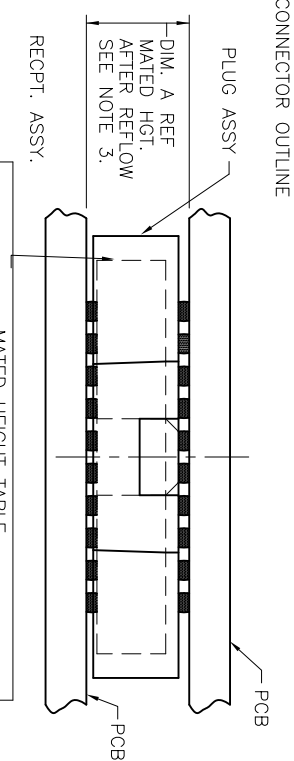
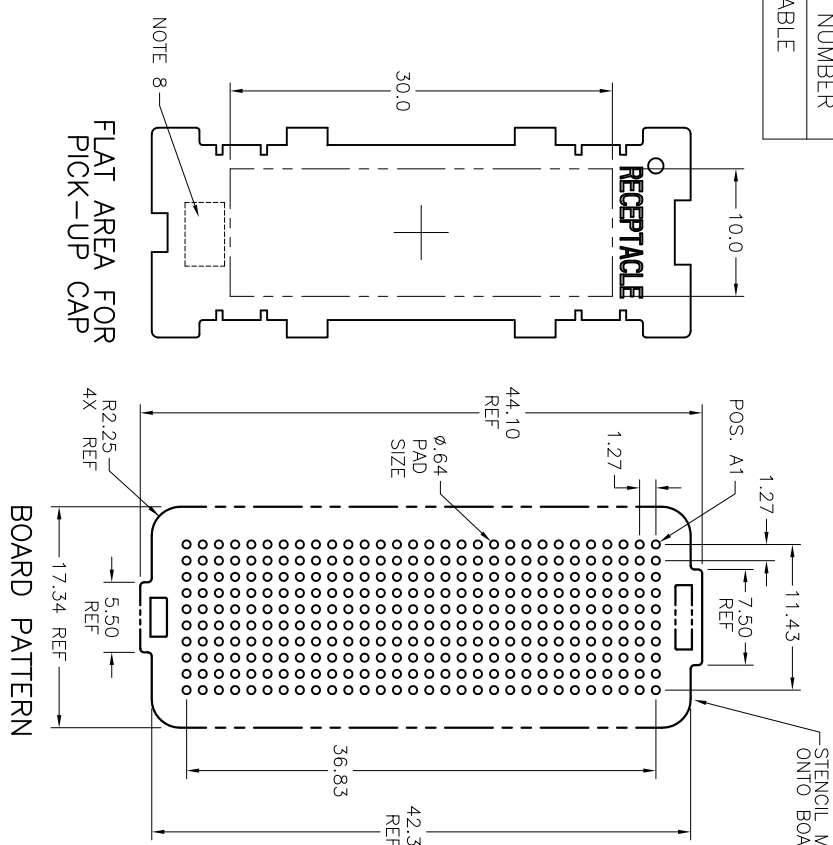
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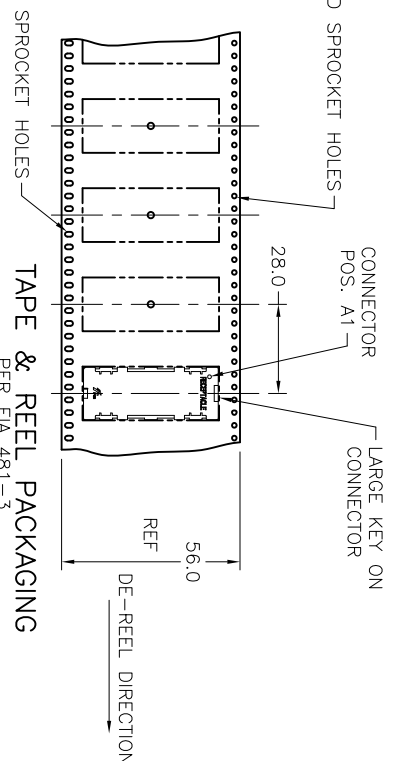
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PRODUCT NUMBER
SEE TABLE



MATED HEIGHT AFTER REFLOW IS BASED ON ϕ .64mm PAD (METAL-DEFINED) AND .13mm SOLDER PASTE STENCIL THICKNESS. SEE NOTE 3.
 END VIEW - MATED CONNECTORS SCALE NONE



TAPE & REEL PACKAGING
 PER EIA 481-3
 SCALE NONE

mat'l code	SEE NOTE 1	date	surface	tolerance	projection	product family
litr	ecm no	date	ASME Y14.5	ASME Y14.5		MEG-ARRAY
S			angles	unless otherwise specified		
			0° ±2°	XXX.13	MM	4mm RECEPTACLE ASSEMBLY
				XXXX.051	Scale: 2:1	10 X 30 = 300 POS.
			dr	D. WAUGHEN		999-12-6
			plqj	D. HARPER		999-12-6
			dlr	D. HARPER		999-12-6
			qdd	D. HARPER		999-12-6
Sheet Index	revision					
	Sheet					

B

A

form: AdminXLC

1

2

3

4

1

2



3

4

B

A

NOTES:

- ① MATERIAL
HOUSING: LCP
CONTACT: COPPER ALLOY
PLATING
CONTACT: (SEE TABLE ON SHEET3)
SOLDER BALL: (SEE TABLE ON SHEET3)
EUTECTIC SnPb OR LEAD FREE
95.5Sn/44Ag/0.5Cu
- ② SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT.
- ③ MATED HEIGHT EFFECTED BY CUSTOMER'S PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE, & SOLDER PASTE.
- ④ PLATING FOR -2XX SERIES PRODUCT NUMBERS MEET THE REQUIREMENTS OF GR-1217-CORE, CENTRAL OFFICE ENVIRONMENT, (25 YEAR LIFE EXPECTANCY). THE CONTACTS IN THESE PRODUCT NUMBERS ALSO HAVE SPECIAL CONTACT GEOMETRY.
- ⑤ FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION.
- ⑥ THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-47-0004 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION.
- ⑦ 84501-A01 AND -A01LF ARE CUSTOMER SPECIALS.
- ⑧ CURRENT COMPANY LOGO TO BE VISIBLE IN APPROXIMATE AREA SHOWN.
- 9. 84501-301, -301LF, -401, -401LF, -501 and -501LF ARE OBSOLETE.
- 10. A  SYMBOL WILL BE NEXT TO ANY DIMENSION, NEW VIEW OR NOTE WHICH HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION
- ⑪ 84501-093LF HAS A SPECIAL CAP 

mat'l code	SEE NOTE 1	surface	tolerance	projection	product family
lfr	eqn no	dr	date	ASME Y14.5	ASME Y14.5
S			angles	MM	MEG-ARRAY
			0° ±2'	Scale: 2:1	4mm RECEPTACLE ASSEMBLY
			dr		10 X 30 = 300 POS.
			plqj		Sheet 4 of 4
			clp		Size
			qdd		A4
Sheet	revision				CUSTOMER Drawing
Index	Sheet				

B

A

A

B